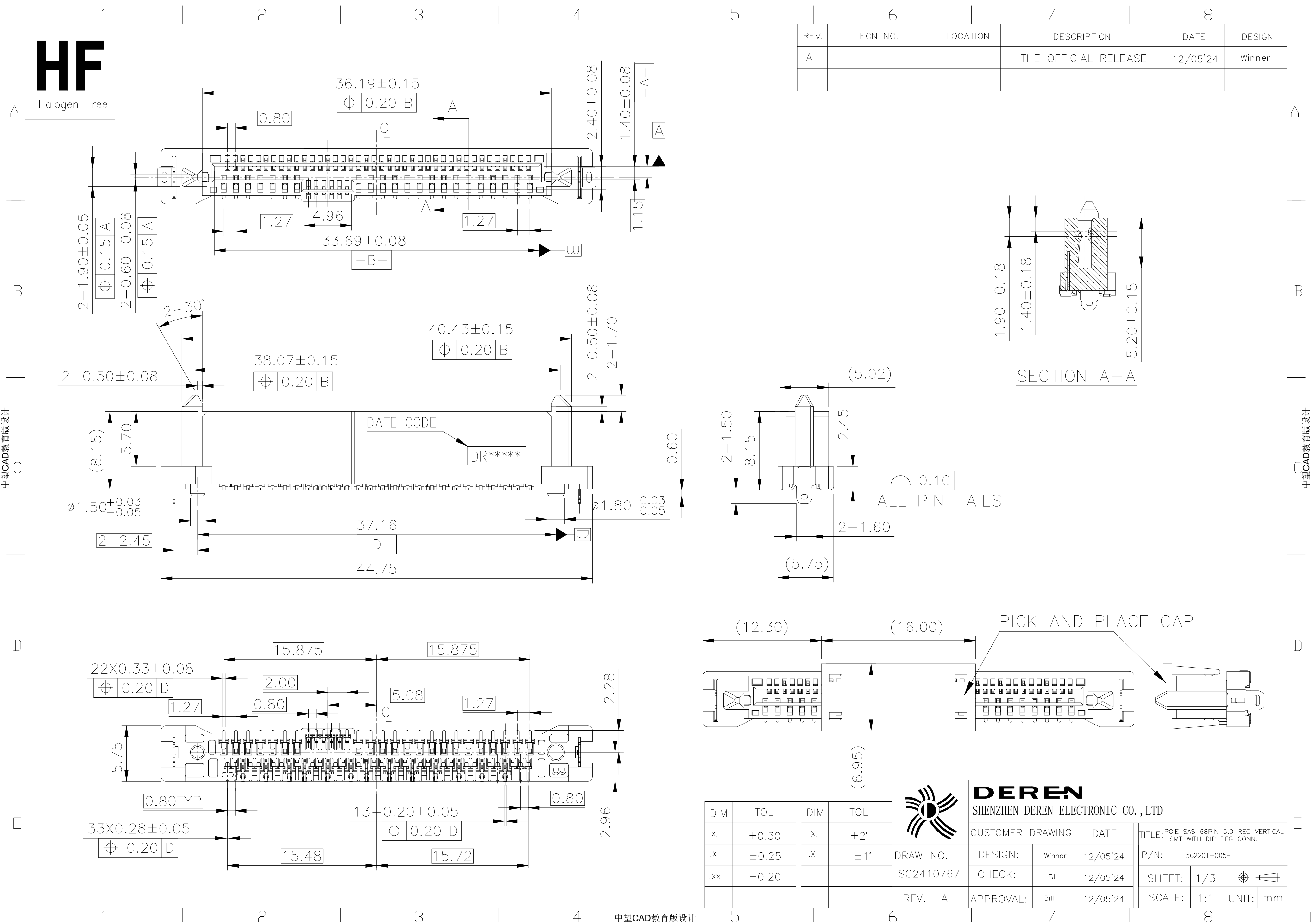




HF

Halogen Free

REV.	ECN NO.	LOCATION	DESCRIPTION	DATE	DESIGN
SEE SHEET 1					

NOTES:

- 1.MATERIAL
- 1.1.HOUSING: HIGH TEMPERATURE THERMOPLASTIC UL94V-0 BLACK;
- 1.2.CAP: HIGH TEMPERATURE THERMOPLASTIC UL94V-0 BLACK;
- 1.3.CONTACT: COPPER ALLOY
- 1.4.PEG: STAINLESS STEEL
2. FINISH:
- 2.1 CONTACT:
- 0.75um[30u"]MIN, Au PLATING ON CONTACT AREA.
- 2.03um [80u"] MIN. TIN PLATING ON SOLDERTAIL AREA.
- 1.27um [50u"] MIN.NICKEL.UNDERPLATING ON ALLOVER AREA.
- 2.2 PEG
- 2.03um [80u"] MIN TIN PLATING OVERALL
- 1.27um [50u"] MIN NICKEL UNDERPLATING OVERALL
3. ELECTRICAL :
- 3-1.CONTACT CURRENT RATING :
- CONTINUOUS CURRENT:1.5A
- PEAK CURRENT:2.5A for 1.5s
- 3-2 CONGACT RESISTANCE: 40mΩ MAX.(INITIAL)
- 3-3.OPERATING TEMPERATURE : -55℃ TO +85℃
- 3-4.VOLTAGE: 30V MAX.
- 3-5.INSULATION RESISTANCE :1000 MEGAOHMS MIN.
- 3-6.DIEELECTRIC WITHSTANDING VOLTAGE :400VAC MIN.
- 3-7.LOW LEVEL CONTACT RESISTANCE :
- 4.MECHANICAL CHARACTERISTICS :
- 4-1.INSERTION FORCE : 65N MAX.
- 4-2.DURABILITY : 500 MATING CYCLES.
5. APPLIED TO REFLOW SOLDERING PROCESS
6. PART NUMBER DESCRIPTION:

562201-005H

CONTACT PLATING CODE:

- 0: Au 30u"
- 1: Au 15u"
- 2: Gold Flash

LOGO CODE:

- 0: W/ DEREN LOGO
- 1: W/O LOGO

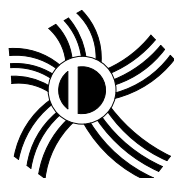


SOLDER PAD

RECOMMEND P.C.B LAYOUT(COMPONENT SIDE)

TOLERANCES: ±0.05;PCB THICKNESS:1.6mm(TOP VIEW)

DIM	TOL	DIM	TOL
x.	±0.30	x.	±2°
.x	±0.25	.x	±1°
.xx	±0.15		



DEREN

SHENZHEN DEREN ELECTRONIC CO.,LTD

CUSTOMER DRAWING

DATE

TITLE: PCIE SAS 68PIN 5.0 REC VERTICAL
SMT WITH DIP PEG CONN.

DESIGN: Winner

12/05'24

P/N: 562201-005H

CHECK: LFJ

12/05'24

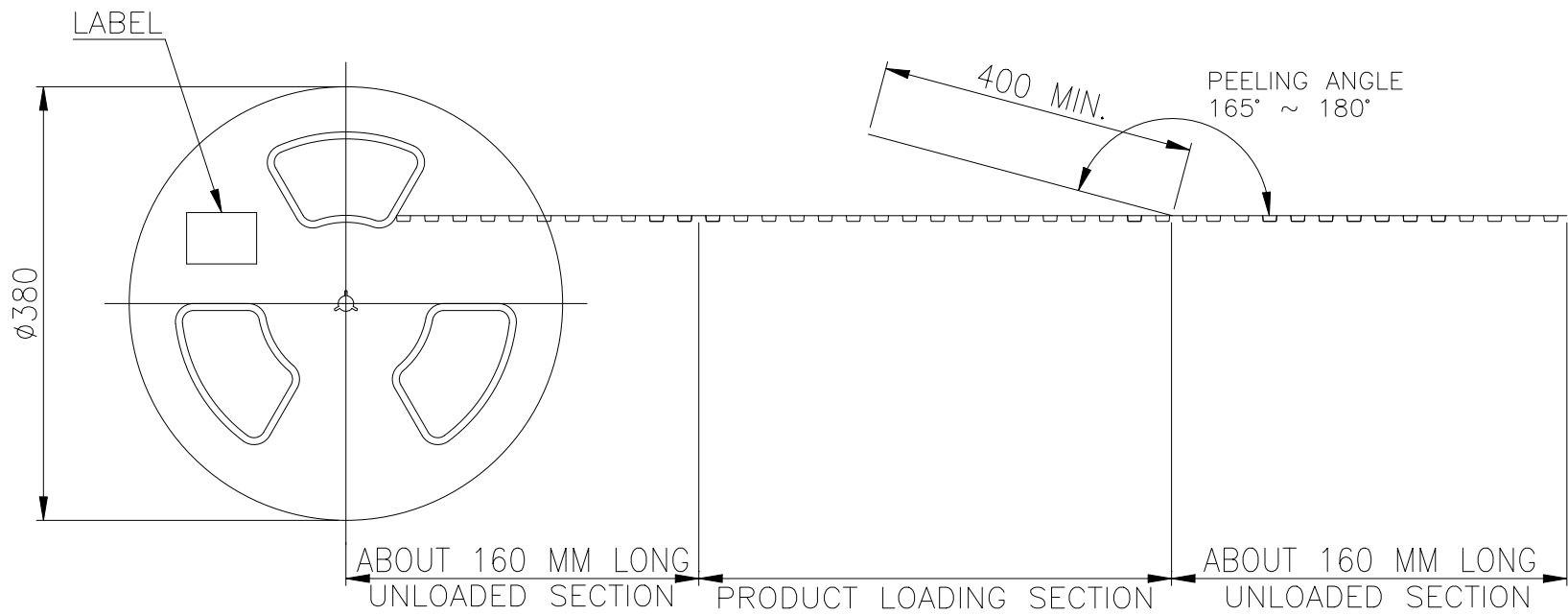
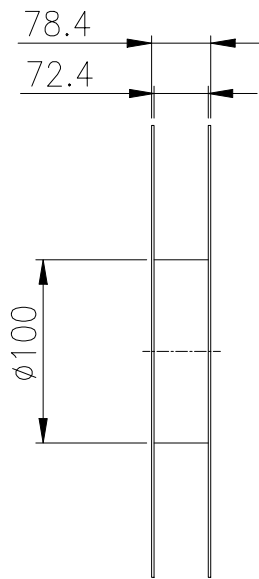
SHEET: 2/3

APPROVAL: Bill

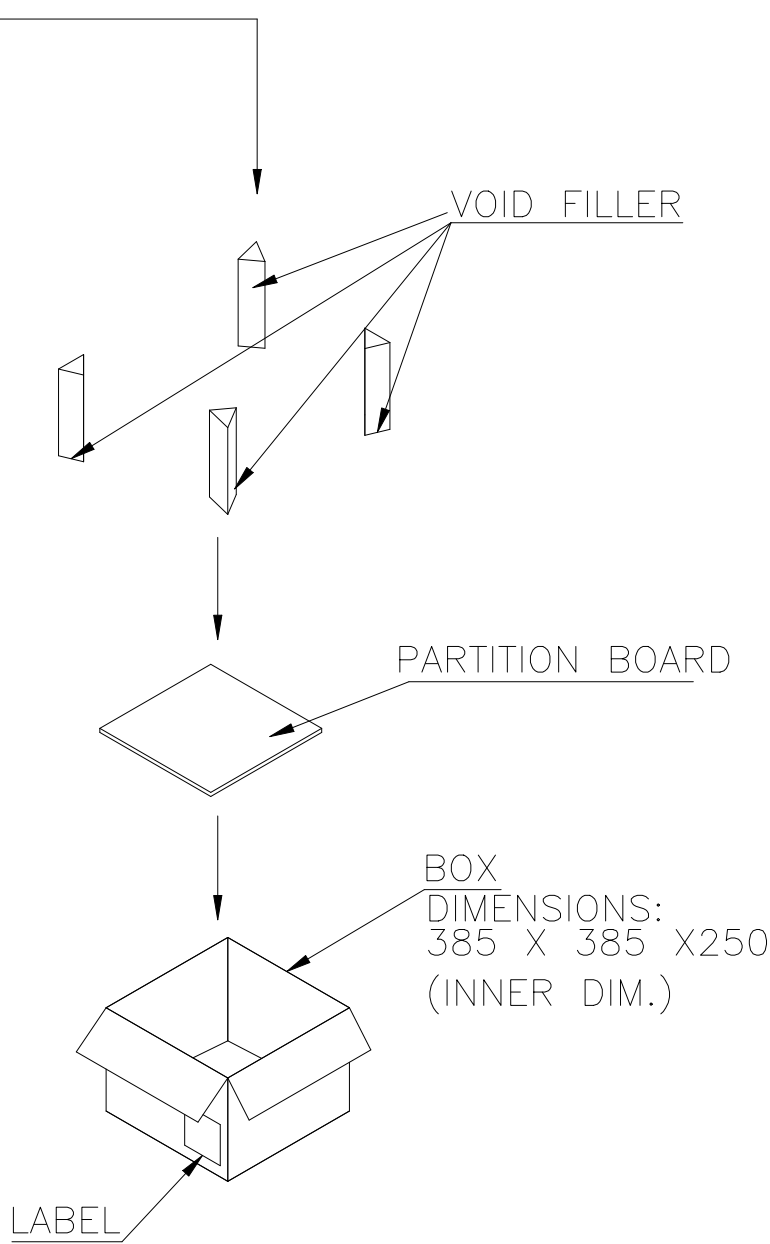
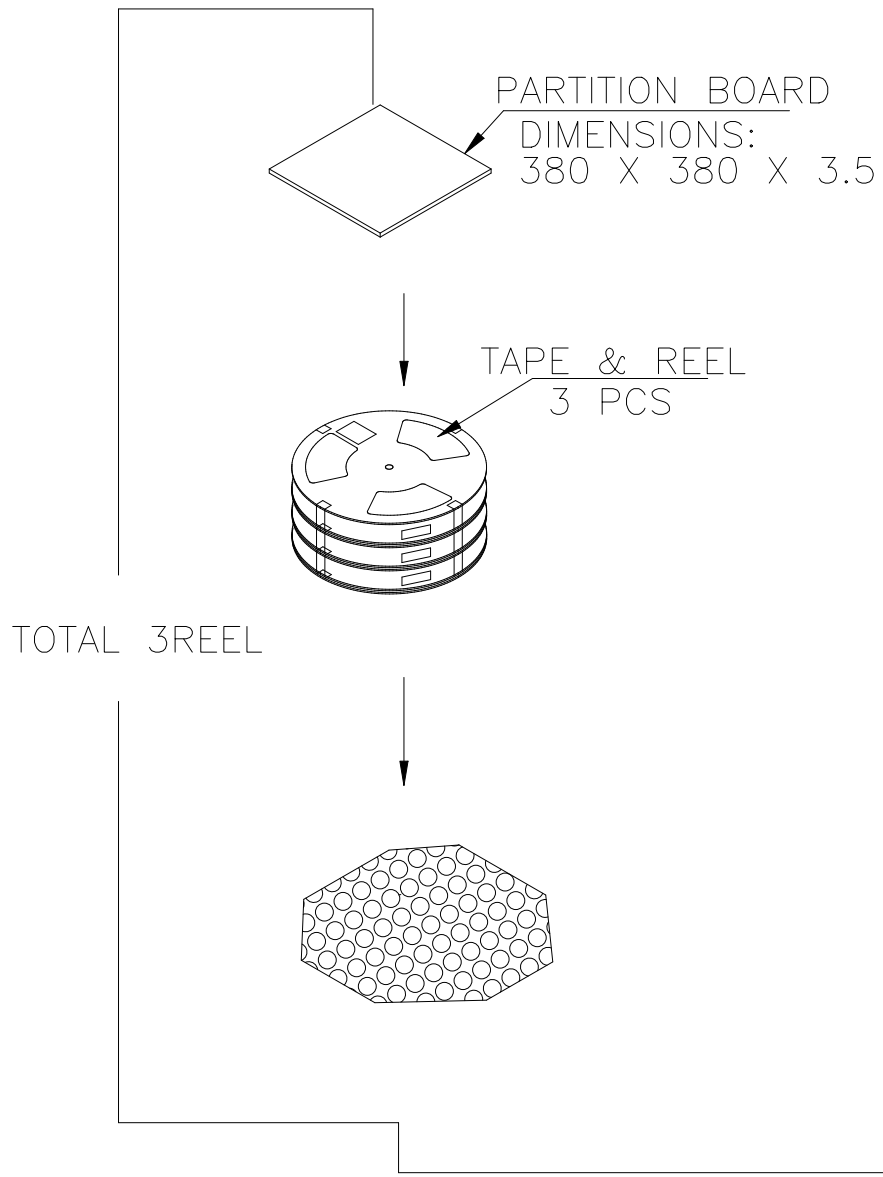
12/05'24

SCALE: 1:1

UNIT: mm

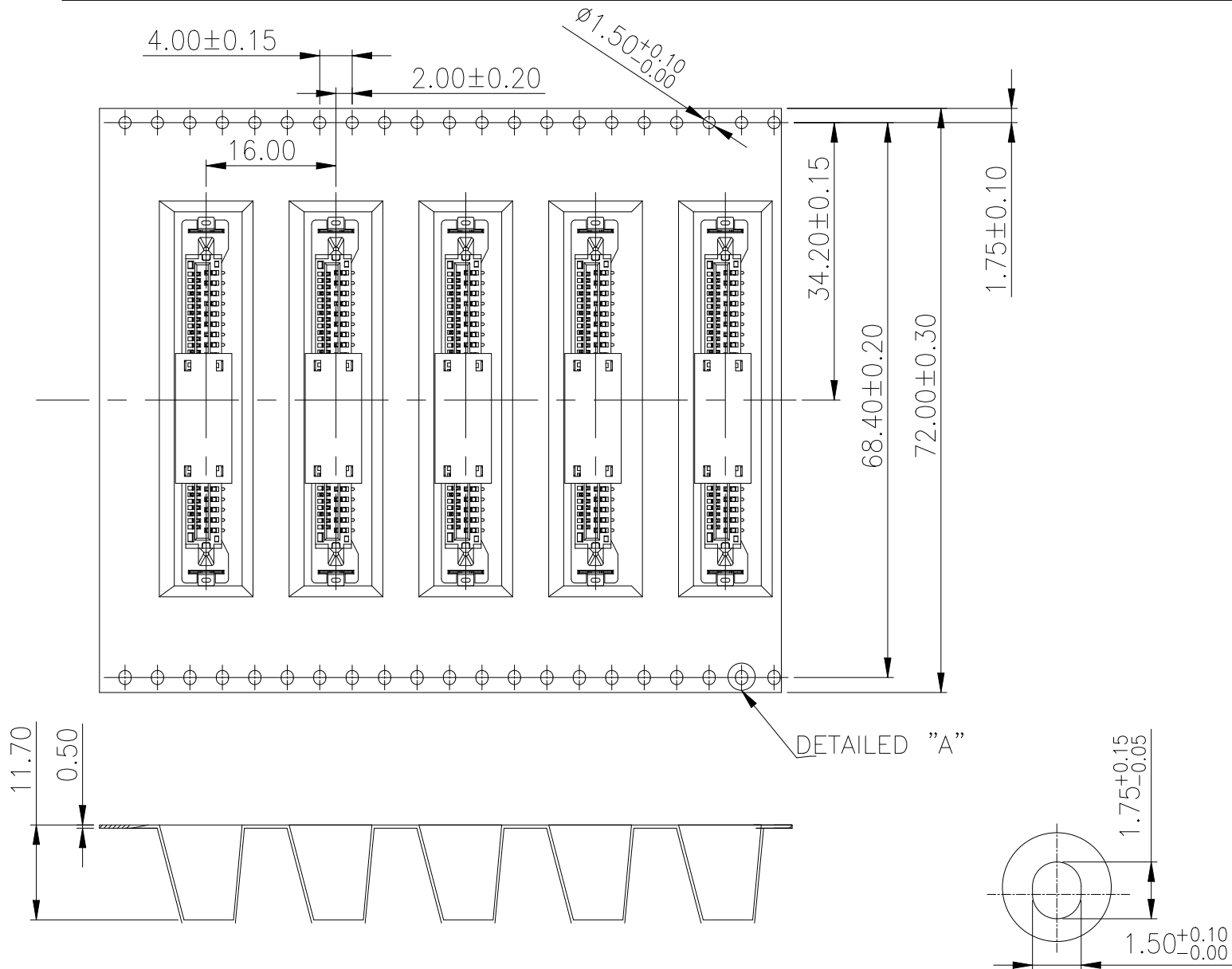


GATHER MATERIAL DIRECTION INPUT MATERIAL DIRECTION



500	3	1500
PCS/TAPE	REELS/BOX	PCS/BOX

REV.	ECN NO.	LOCATION	DESCRIPTION	DATE	DESIGN
SEE SHEET 1					



- NOTES : (FOR TAPE & REEL)
PACKAGING MATERIAL IN PLASTIC, RUBBER, INK, PIGMENT AND PAINT MUST MEET DEREN CONTROLLED SUBSTANCES SPEC.
* CADMIUM AND CADMIUM COMPOUNDS NOT TO EXCEED: 5 PPM.
* LEAD, CADMIUM, CHROM VI AND MERCURY NOT TO EXCEED: 100 PPM (COMBINED).
* CARRIER TAPES, COVER TAPES, REELS AND TAPED COMPONENTS MUST MEET THE REQUIREMENTS DEFINED PER EIA-481-B.
1. MATERIAL :
COVER TAPE : PET, COLOR: CLEAR
CARRIER TAPE : PS
REEL : PS
SHIPPING BOX: CORRUGATED FIBER
2. DIMENSION :
REEL : SEE DRAWING
BOX : SEE DRAWING
3. QUANTITY : SEE TABLE
4. WEIGHT : SEE TABLE
5. PEELING RESISTANCE : 10gf~100gf (for 8mm)
10gf~130gf (for 12mm~56mm)
10gf~150gf (for 72mm)
6. PEELING SPEED : 300mm/MINUTES

	DEREN SHENZHEN DEREN ELECTRONIC CO.,LTD			
	CUSTOMER DRAWING		DATE	TITLE: PCIE SAS 68PIN 5.0 REC VERTICAL SMT WITH DIP PEG CONN.
	DRAW NO.	DESIGN:	Winner	P/N: 562201-005H
	SC2410767	CHECK:	LFJ	SHEET: 3/3
REV.	A	APPROVAL:	Bill	SCALE: N/A
				UNIT: mm